



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2019-12-20
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMS MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
PW6BAARP	CS6P*0082BF6	A	Z9LA	2019-12-20
	Amount	UoM	Unit type	ST ECOPACK Grade
	35	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	0	

Package Designator	Size	Nbr of instances	Shape
TSSOP 8	3X4.4X1	8	bulk solder
Comment	TSSOP 8 BODY 4.4 PITCH 0.65		

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
Exemption Id.	Description

QueryList : California Prop65 list, dated 13th September 2019			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.02	alloy	688

QueryList : REACH-16th July 2019				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update				
Query				Response
The Product does contain at least one of the substances listed in Chemical Control Act				NO
Substance	Homogeneous Material impacted	Content in Homogeneous Material (mg)	Concentration in the material(%)	Application Purpose

Material Composition Declaration :						Mfr Item Name	CS6P*0082BF6				8562516.0	999226.0
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	1.356	mg	supplier	die	Silicon(Si)	7440-21-3		1.332	mg	982301	38177
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.011	mg	8112	315
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.006	mg	4425	172
				supplier	passivation	Silicon oxide	7631-86-9		0.007	mg	5162	201
Leadframe	Copper & its alloys	11.236	mg	supplier	Alloy	Cu	7440-50-8		11.775	mg	952131	337489
				supplier	Alloy	Si	7439-89-6		0.112	mg	9056	3210
				supplier	Alloy	Ni	7723-14-0		0.402	mg	32506	11522
				supplier	Alloy	Mg	7440-66-6		0.011	mg	889	315
				supplier	Alloy	Ag	7440-22-4		0.067	mg	5418	1920
Die attach	Other Organic Materials	0.149	mg	supplier	Solder	Silver	7440-22-4		0.116	mg	9380	3325
				supplier	Solder	Acrylate monomer	61434-04-6		0.018	mg	120805	516
				supplier	Solder	Acrylate oligomer	Proprietary		0.010	mg	67114	287
				supplier	Solder	Bismaleimide resin	Proprietary		0.004	mg	26846	115
Bonding wire	Other inorganic materials	0.670	mg	supplier	Solder	Epoxy resin	26875-67-2		0.001	mg	6711	29
				supplier	Bonding wire	Cu	7440-50-8		0.670	mg	54176	19203
				supplier	Bonding wire	Pd	7440-05-3		0.020	mg	28986	573
Encapsulation	Other Organic Materials	19.691	mg	supplier	Mold compound	Epoxy Resin 1	Proprietary		0.098	mg	657718	2809
				supplier	Mold compound	Epoxy Resin 2	Proprietary		0.098	mg	657718	2809
				supplier	Mold compound	Epoxy Resin 3	Proprietary		0.098	mg	657718	2809
				supplier	Mold compound	Phenol Resin	Proprietary		0.494	mg	3315436	14159
				supplier	Mold compound	Carbon black	1333-86-4		0.020	mg	984	573
				supplier	Mold compound	Amorphous silica	60676-86-0		19.296	mg	949233	553052
				supplier	Mold compound	Crystal silica	14808-60-7		0.197	mg	9691	5646